

Title (en)

PROCESS FOR COATING USING THERMAL SPRAYING AND ELECTROPLATING

Title (de)

VERFAHREN ZUM BESCHICHTEN DURCH THERMISCHEN SPRITZEN UND GALVANISCHE PLATTIERUNG

Title (fr)

PROCÉDÉ DE REVÊTEMENT PAR PULVÉRISATION THERMIQUE ET PLACAGE ÉLECTROCHIMIQUE

Publication

**EP 2516698 B1 20140402 (DE)**

Application

**EP 10784289 A 20101119**

Priority

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Abstract (en)

[origin: WO2011076499A1] The invention relates to a method for coating a work piece, wherein a layer is electrochemically produced from a first material (28). In order to generate an inhomogeneous expansion behavior of the layer, according to the invention a thermal spraying, in particular a cold gas spraying, achieves that specific zones (27) are created in the layer (29) from a material having a different thermal expansion behavior. Said zones expand more laterally than in the direction of the layer thickness so that directed internal stresses occur in the layer (29) upon heating or cooling of the component (11), which can be specifically utilized depending on the design conditions of the component (11).

IPC 8 full level

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